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With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

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2SK2593G

Silicon N-channel junction FET

For low-frequency amplification For switching circuits

■ Features

- Low noise figure NF
- \bullet High gate-drain voltage (source open) V_{GDO}
- SSMini type package, allowing downsizing of the equipment and automatic insertion through the tape packing.

■ Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit	
Drain-sourse voltage	V_{DS}	55	V	
Gate-drain voltage (Source open)	V_{GDO}	-55	V	
Gate-source voltage (Drain open)	V_{GSO}	-55	V	
Drain current	I_{D}	30	mA	
Gate current	I_G	10	mA	
Power dissipation	P_{D}	125	mW	
Channel temperature	T _{ch}	125	°C	
Storage temperature	T _{stg}	-55 to +125	°C	

Package

- Code SSMini3-F3
- Pin Name
 - 1: Source
 - 2: Drain
- 3: Gate

■ Marking Symbol: 2B

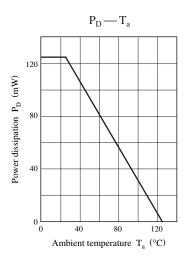
■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

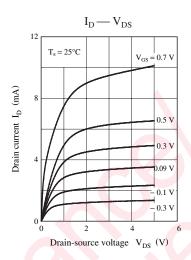
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Gate-drain surrender voltage	V _{GDS}	$I_G = -100 \ \mu A, \ V_{DS} = 0$	-55	0),		V
Drain-source current *	I_{DSS}	$V_{DS} = 10 \text{ V}, V_{GS} = 0$	1.0	0.	6.5	mA
Gate-source cutoff current	I_{GSS}	$V_{GS} = -30 \text{ V}, V_{DS} = 0$	~ 600.		-10	nA
Gate-source cutoff voltage	V _{GSC}	$V_{DS} = 10 \text{ V}, I_{D} = 10 \mu\text{A}$			-5	V
Forward transfer admittance	Y _{fs}	$V_{DS} = 10 \text{ V}, I_D = 5 \text{ mA}, f = 1 \text{ kHz}$	2.5	7.5		mS
Short-circuit forward transfer capacitance (Common source)	C _{iss}	$V_{DS} = 10 \text{ V}, V_{GS} = 0, f = 1 \text{ MHz}$		6.5		pF
Reverse transfer capacitance (Common source)	C _{rss}	26 112 1/Mg.		1.9		pF
Noise figure	NF	$V_{DS} = 10 \text{ V}, V_{GS} = 0, f = 100 \text{ Hz}$ $R_g = 100 \text{ k}\Omega$		2.5		dB

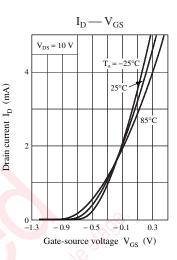
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

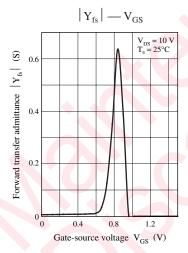
2. *: Rank classification

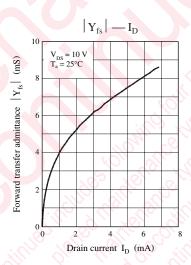
Rank	Р	Q
I _{DSS} (mA)	1.0 to 3.0	2.0 to 6.5





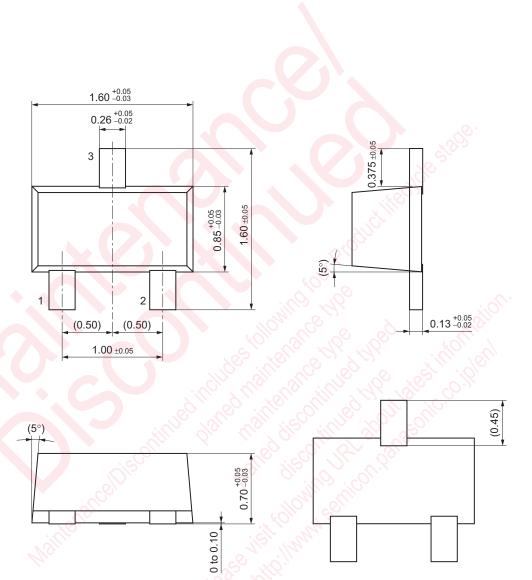






2 SJF00064BED

SSMini3-F3 Unit: mm



SJF00064BED 3

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